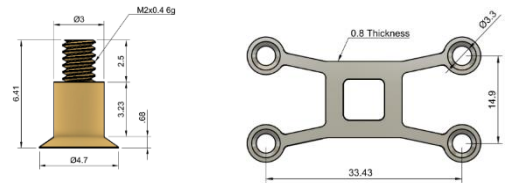


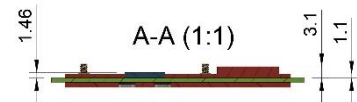
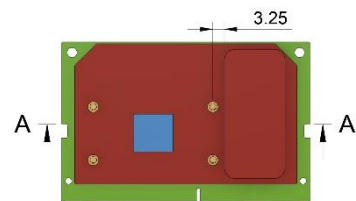
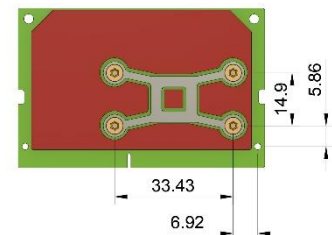
Heatsink / Heatspreader / Leaf spring

The Nano leaf spring kits for secure mounting of cooling solutions. This ensures optimal thermal interface while minimizing the risk of damaging the module.



Implementation guidelines

- Refer to Nvidia Jetson Nano Thermal Design Guide for thermal dissipation requirements
- Use M2x0.4 thread with at least 3mm depth fully formed thread in heatspreader/sink
- Recommended material for heatsink is aluminum or copper
- Use intermediate heat transfer compound (paste or pad), do not screw the module directly to heatsink/heat spreader or case
- When using heatspreader use thermal pad >0.5mm between heatspreader and case to ensure thermal conductivity
- Do not cover the module envelope
- Use <0.15Nm for M2 screws
- Handle module with care during assembly (ESD)
- Ensure correct orientation of the spring. The leaf spring should only contact the module in the middle
- SO-DIMM connector spacers must be used to reduce stress on the PCB



RED: module envelope, keep out zone for component clearance
 BLUE: Processor die
 GREEN: PCB + underside
 The envelope for thermal solution 3D model is available in the Nvidia developer download area



Leaf spring kit Nano:

Each kit includes

- Leaf spring (155-0713-000)
- 4 screws (155-0717-000)

Cooling kit Nano:

Each kit includes

- Leaf spring (155-0713-000)
- 4 screws (155-0717-000)
- Heat sink Nano (110-0286-000)

SKU	Kit
70754	Leaf spring kit Nano
70794	Cooling kit Nano
70750-40	Heatspreader 38x30x4.0mm Nano
70750-46	Heatspreader 38x30x4.6mm Nano
70750-50	Heatspreader 38x30x5.0mm Nano
70752	Heat sink Nano (110-0286-000)

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